



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20240202003.1

**Qualification of FFAB using qualified Process Technology, Die Revision, and additional Assembly BOM options for select devices
Change Notification / Sample Request**

Date: February 02, 2024

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team
SC Business Services

20240202003.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
INA114AP	NULL
INA114AU	NULL
INA114AU/1K	NULL
INA114BP	NULL
INA114BU	NULL
INA114BU/1K	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240202003.1	PCN Date:	February 02, 2024
Title:	Qualification of FFAB using qualified Process Technology, Die Revision, and additional Assembly BOM options for select devices		
Customer Contact:	Change Management team	Dept:	Quality Services
Proposed 1st Ship Date:	May 2, 2024	Estimated Sample Availability:	Mar 2, 2024*
*Sample requests received after March 2, 2024 will not be supported.			
Change Type:			
<input type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/> Design	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/>	Wafer Fab Materials
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process
PCN Details			
Description of Change:			
Texas Instruments is pleased to announce the qualification of a new fab & process technology (FFAB, BICOM3XHV) and assembly BOM options for selected devices as listed below in the product affected section.			
Current Fab Site			Additional Fab Site
Current Fab Site	Process	Wafer Diameter	Additional Fab Site
SFAB	JIBB	150 mm	FFAB
			BICOM3XHV
			200 mm
The die was also changed as a result of the process change.			
Assembly BOM options are noted below:			
What	Current	Additional	
Bond wire composition, diameter	Au, 1.2 mils or Cu, 0.96 mil	Cu, 0.8 mils	
Mount Compound	4205846	4147858	
Mold Compound	4209640	4211880	
Qual details are provided in the Qual Data Section.			
Reason for Change:			
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			
Impact on Environmental Ratings:			
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.			
RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
FR-BIP-1	TID	DEU	Freising

Die Rev:

Current

New

Die Rev [2P]	Die Rev [2P]
A, B	A

Sample product shipping label (not actual product label)


TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:


G4



(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) 630: SHE (21L) 660: USA
 (22L) AS0: MLA (23L) ACO: MYS

MSL '2 / 260C / 1 YEAR SEAL DT
 MSL 1 / 235C / UNLIM 03/29/04
 OPT:
 ITEM: 39
 LBL: 5A (L)T0:1750

Product Affected:

INA114AP	INA114AU/1K	INA114BU
INA114AU	INA114BP	INA114BU/1K

For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: INA114AU/1K	Qual Device: INA114AP	QBS Package Reference: NE5532P	QBS Package Reference: UGC37322P	QBS Process Reference: INA821ID	QBS Process Reference: OPA207ID	QBS Package Reference: INA2128U/1K	QBS Package Reference: OP07CP
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	3/231/0	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0	1/77/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	3/231/0	3/231/0	1/77/0	1/77/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0	3/231/0	3/231/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	3/231/0	3/231/0	-	-
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	-	3/66/0	3/66/0	-	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	-	-	-	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-	-	1/3/0	1/3/0	1/3/0	-

Type	#	Test Name	Condition	Duration	Qual Device: INA114AU/1K	Qual Device: INA114AP	QBS Package Reference: NE5532P	QBS Package Reference: UCC37322P	QBS Process Reference: INA821ID	QBS Process Reference: OPA207ID	QBS Package Reference: INA2128U/1K	QBS Package Reference: OP07CP
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	1/3/0	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	1/6/0	1/3/0	1/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/5/0	-	-	3/90/0	1/30/0	1/30/0	1/30/0

- QBS: Qual By Similarity
- Qual Device INA114AU/1K is qualified at MSL1 260C
- Qual Device INA114AP is qualified at NOT CLASSIFIED 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2212-035

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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